



ULTRA PRECISION 4x4 CML SWITCH WITH INTERNAL I/O TERMINATION

Precision Edge™
SY58040U

FEATURES

- Provides crosspoint switching between any input pair to any output pair
- Guaranteed AC performance over temperature and voltage:
 - DC to >5Gbps throughput
 - <350ps propagation delay
 - <60ps t_r / t_f times
 - <25ps skew (output-to-output)
- Unique, patent-pending, channel-to-channel isolation design provides superior crosstalk performance
- Ultra-low jitter design:
 - <1ps_{rms} random jitter
 - <10ps_{pp} deterministic jitter
 - <10ps_{pp} total jitter (clock)
 - <0.7ps_{rms} crosstalk-induced jitter
- Unique, patent-pending, 50Ω input termination extended CMVR, and VT pin accepts DC- and AC-coupled differential inputs
- 400mV CML output swing
- 50Ω source terminated outputs minimize round-trip reflections
- Power supply 2.5V ±5% or 3.3V ±10%
- -40°C to +85°C temperature range
- Available in 44-pin (7mm × 7mm) MLF™ package



Precision Edge™

DESCRIPTION

The SY58040U is a low jitter, low skew, high-speed 4x4 crosspoint switch optimized for precision telecom and enterprise server/storage distribution applications. The SY58040U distributes clock frequencies from DC to 4GHz, and data rates to 5Gbps guaranteed over temperature and voltage.

The SY58040U differential input includes Micrel's unique, 3-pin input termination architecture that directly interfaces to any differential signal (AC or DC-coupled) as small as 100mV (200mV_{pp}) without any level shifting or termination resistor networks in the signal path. The outputs are 50Ω source-terminated CML with extremely fast rise/fall times guaranteed to be less than 60ps.

The SY58040U features a patent-pending isolation design that significantly improves on channel-to-channel crosstalk performance.

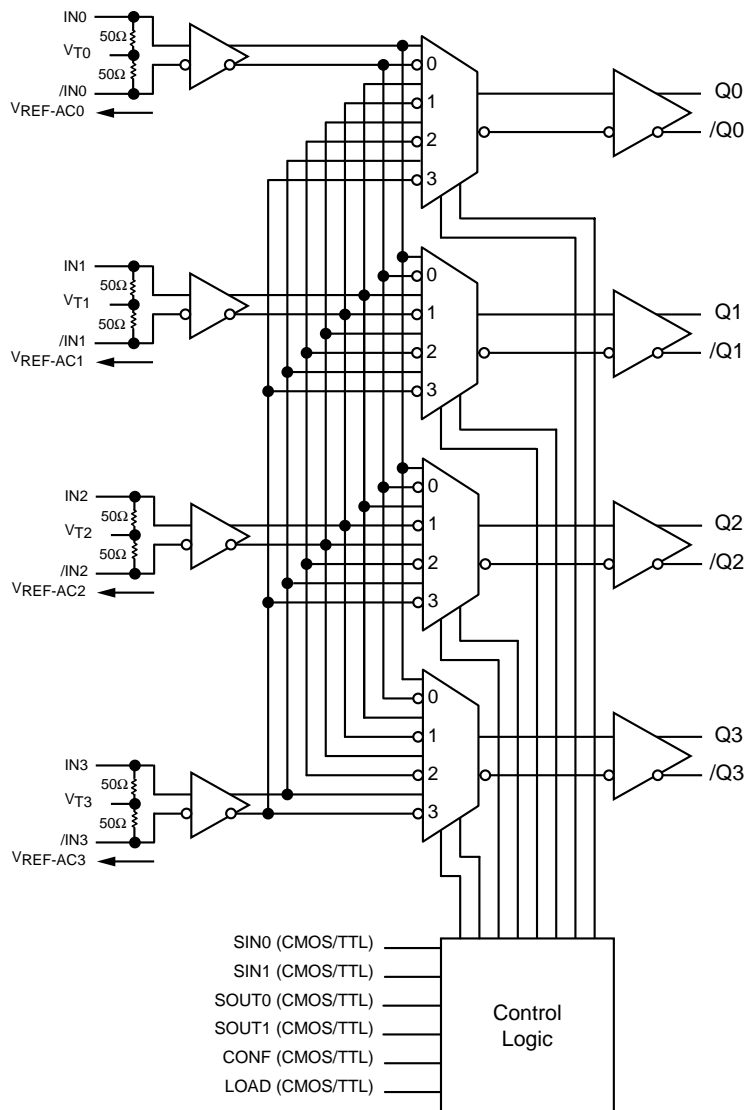
The SY58040U operates from a 2.5V ±5% or 3.3V ±10% supply and is guaranteed over the full industrial temperature range of -40°C to +85°C. The SY58040U is part of Micrel's high-speed, Precision Edge™ product line.

Data sheets and support documentation can be found on Micrel's web site at www.micrel.com.

APPLICATIONS

- Data communication systems
- All SONET/SDH data/clock applications
- All Fibre Channel applications
- All Gigabit Ethernet applications

FUNCTIONAL BLOCK DIAGRAM



TRUTH TABLES

SIN1	SIN0	INPUT
0	0	IN0
0	1	IN1
1	0	IN2
1	1	IN3

SOUT1	SOUT0	OUTPUT
0	0	Q0
0	1	Q1
1	0	Q2
1	1	Q3

Absolute Maximum Ratings⁽¹⁾

Power Supply Voltage (V_{CC}) -0.5V to +4.0V
 Input Voltage (V_{IN}) -0.5V to V_{CC}
 CML Output Voltage (V_{OUT}) $V_{CC} - 0.5V$ to $V_{CC} + 5.0V$
 Termination Current⁽³⁾
 Source or sink current on VT pin $\pm 100mA$
 Input Current⁽³⁾
 Source or sink current on IN, /IN $\pm 50mA$
 V_{REF-AC} Current⁽³⁾
 Source or sink current on IN, /IN $\pm 2mA$
 Lead Temperature (soldering, 10 sec.) 265°C
 Storage Temperature Range (T_S) -65°C to +150°C

Operating Ratings⁽²⁾

Power Supply Voltage (V_{CC}) +2.375V to +3.60V
 Ambient Temperature Range (T_A) -40°C to +85°C
 Package Thermal Resistance⁽⁴⁾
 MLF™ (θ_{JA})
 Still-Air 23°C/W
 MLF™ (ψ_{JB})
 Junction-to-board 12°C/W

DC ELECTRICAL CHARACTERISTICS⁽⁵⁾

$T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{CC}	Power Supply Voltage	$V_{CC} = 2.5V$.	2.375	2.5	2.625	V
		$V_{CC} = 3.3V$.	3.0	3.3	3.6	V
I_{CC}	Power Supply Current	No load, max. V_{CC} . Includes current from internal 50Ω pull-up on each output.		225	300	mA
R_{IN}	Input Resistance (IN-to- V_T , /IN-to- V_T)		40	50	60	Ω
R_{DIFF_IN}	Differential Input Resistance (IN-to-/IN)		80	100	120	Ω
V_{IH}	Input HIGH Voltage (IN-to-/IN)	Note 6	$V_{CC}-1.6$		V_{CC}	V
V_{IL}	Input LOW Voltage (IN-to-/IN)		0		$V_{IH}-0.1$	V
V_{IN}	Input Voltage Swing (IN-to-/IN)	See Figure 1a.	0.1		1.7	V
V_{DIFF_IN}	Differential Input Voltage Swing $ IN - /IN $	See Figure 1b.	0.2			V
V_{T_IN}	IN to V_T (IN-to-/IN)				1.28	V
V_{REF-AC}	Output Reference Voltage		$V_{CC}-1.3$	$V_{CC}-1.2$	$V_{CC}-1.1$	V

Notes:

1. Permanent device damage may occur if ratings in the "Absolute Maximum Ratings" section are exceeded. This is a stress rating only and functional operation is not implied for conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Due to the limited drive capability, use for input of the same package only.
4. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. θ_{JA} uses 4-layer in still-air number, unless otherwise stated.
5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
6. V_{IH} (min), not lower than 1.2V.

CML OUTPUT DC ELECTRICAL CHARACTERISTICS⁽⁷⁾

$V_{CC} = 2.5V \pm 5\%$ or $3.3V \pm 10\%$; $T_A = -40^\circ C$ to $+85^\circ C$; $R_L = 100\Omega$ across each output pair, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OH}	Output HIGH Voltage Q, /Q		$V_{CC}-0.040$	$V_{CC}-0.010$	V_{CC}	V
V_{OUT}	Output Differential Swing Q, /Q	See Figure 1a.	325	400		mV
V_{DIFF_OUT}	Differential Output Voltage Swing Q, /Q	See Figure 1b.	650	800		mV
R_{OUT}	Output Source Impedance		40	50	60	Ω

LVTTL/CMOS DC ELECTRICAL CHARACTERISTICS⁽⁷⁾

$V_{CC} = 2.5V \pm 5\%$ or $3.3V \pm 10\%$; $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{IH}	Input HIGH Voltage		2.0		V_{CC}	V
V_{IL}	Input LOW Voltage				0.8	V
I_{IH}	Input HIGH Current		-125		30	μA
I_{IL}	Input LOW Current	$V_{IL} = 0V$.	-300			μA

Note:

7. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC ELECTRICAL CHARACTERISTICS⁽⁸⁾

$V_{CC} = 2.5V \pm 5\%$ or $3.3V \pm 10\%$; $T_A = -40^\circ C$ to $+85^\circ C$, $R_L = 100\Omega$ across each output pair, unless otherwise stated.

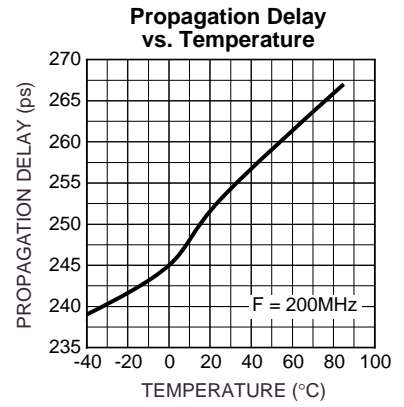
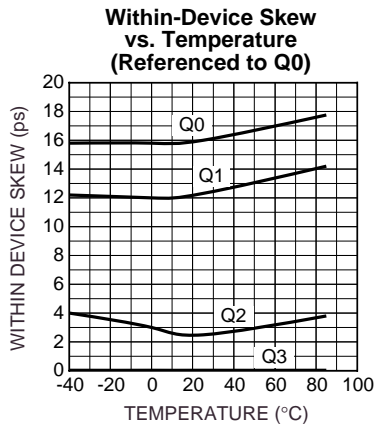
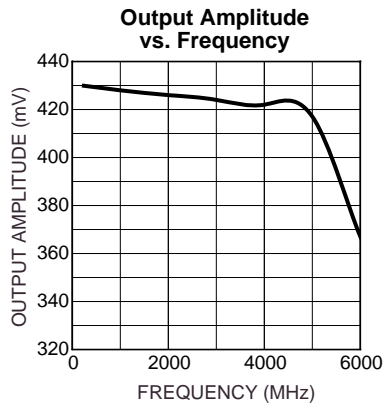
Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{MAX}	Maximum Operating Frequency	NRZ data	5			Gbps
		$V_{OUT} \geq 200mV$ Clock		3		GHz
t_{pd}	Differential Propagation Delay	IN-to-Q	150	225	350	ps
		CONFIG-to-Q			500	ps
Δt_{pd} Tempco	Differential Propagation Delay Temperature Coefficient			225		fs/ $^\circ C$
t_S	Set-Up Time	SIN-to-LOAD	800			ps
		SOUT-to-LOAD	800			ps
		LOAD-to-CONFIG	800			ps
		CONFIG-to-LOAD	950			ps
t_H	Hold Time LOAD-to-SIN, LOAD-to-SOUT		800			ps
t_{SKEW}	Output-to-Output Skew	Note 9			25	ps
	Part-to-Part Skew	Note 10			150	ps
t_{JITTER}	Data	Random Jitter (RJ)	Note 11		1	ps_{rms}
		Deterministic Jitter (DJ)	Note 12		10	ps_{pp}
	Clock	Cycle-to-Cycle Jitter	Note 13		1	ps_{rms}
		Total Jitter (TJ)	Note 14		10	ps_{pp}
	Crosstalk-induced Jitter	Note 15			0.7	ps_{rms}
t_r, t_f	Output Rise/Fall Time	At full output swing, 20% to 80%.	20	40	60	ps

Notes:

8. High-frequency AC-parameters are guaranteed by design and characterization.
9. Output-to-output skew is measured between two different outputs under identical input transitions.
10. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs
11. Random jitter is measured with a K28.7 character pattern, measured at $<f_{MAX}$.
12. Deterministic jitter is measured at 2.5Gbps/3.2Gbps, with both K28.5 and $2^{23}-1$ PRBS pattern.
13. Cycle-to-cycle jitter definition: the variation of periods between adjacent cycles, $T_n - T_{n-1}$ where T is the time between rising edges of the output signal.
14. Total jitter definition: with an ideal clock input of frequency $<f_{MAX}$, no more than one output edge in 10^{12} output edges will deviate by more than the specified peak-to-peak jitter value.
15. Crosstalk induced jitter is defined as the added jitter that results from signals applied to two adjacent channels. It is measured at the output while applying two similar differential clock frequencies that are asynchronous with respect to each other at the inputs.

TYPICAL OPERATING CHARACTERISTICS

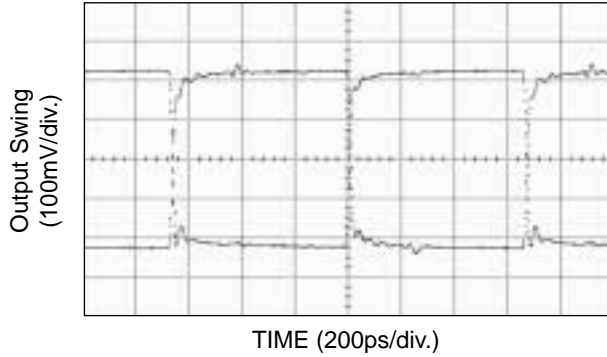
$V_{CC} = 3.3V$, $GND = 0$, $V_{IN} = 100mV$, $T_A = 25^{\circ}C$, unless otherwise stated.



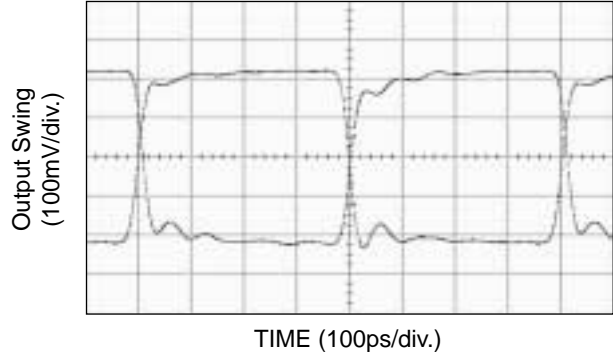
FUNCTIONAL CHARACTERISTICS

$V_{CC} = 3.3V$, $GND = 0$, $V_{IN} = 100mV$, $T_A = 25^\circ C$, unless otherwise stated.

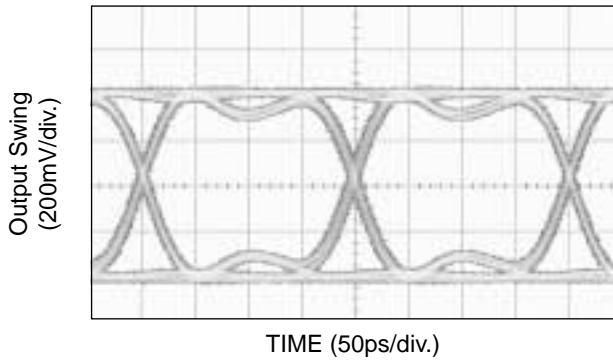
200MHz Output



622MHz Output



5Gbps Output (Q - /Q)



SINGLE-ENDED AND DIFFERENTIAL SWINGS

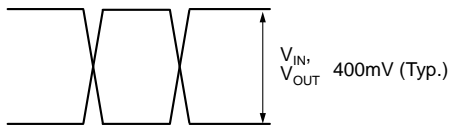


Figure 1a. Single-Ended Voltage Swing

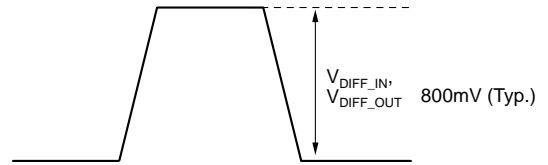


Figure 1b. Differential Voltage Swing

INPUT AND OUTPUT STAGES

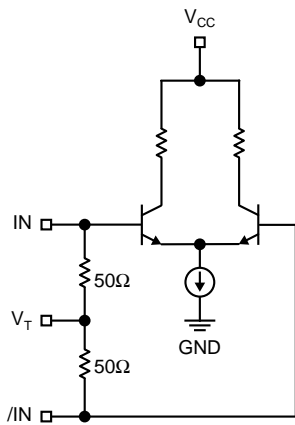


Figure 2a. Simplified Differential Input Stage

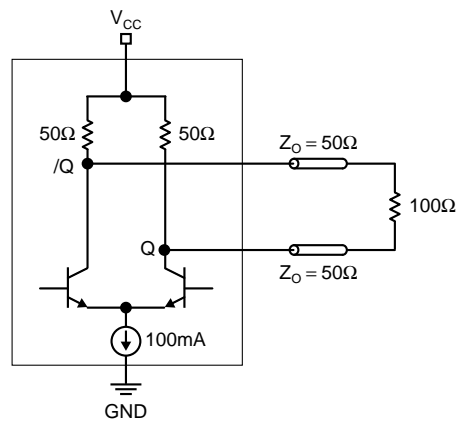


Figure 2b. CML DC-Coupled (100Ω Termination)

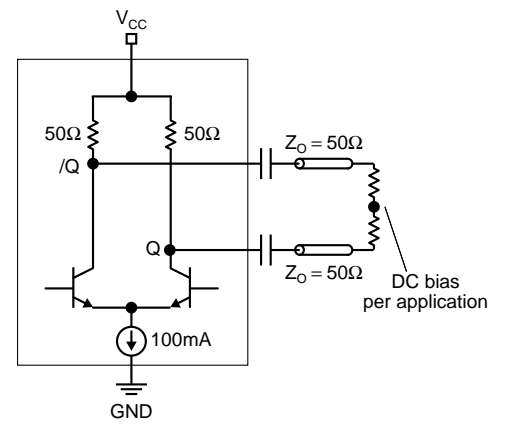


Figure 2c. CML AC-Coupled (50Ω Termination)

INPUT INTERFACE APPLICATIONS

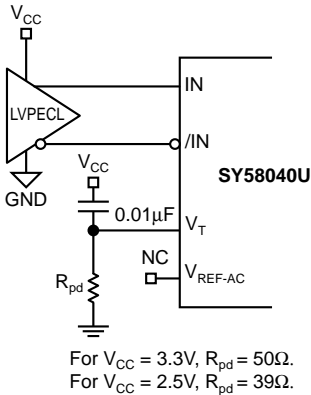


Figure 3a. LVPECL Interface (DC-Coupled)

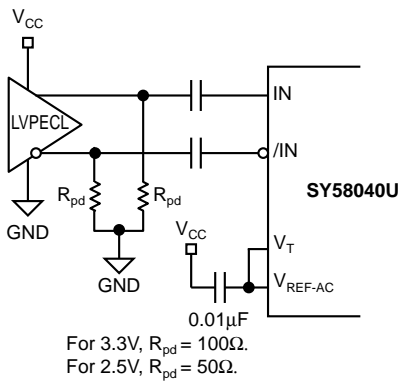


Figure 3b. LVPECL Interface (AC-Coupled)

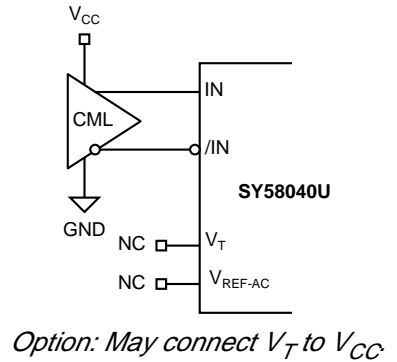


Figure 3c. CML Interface (DC-Coupled)

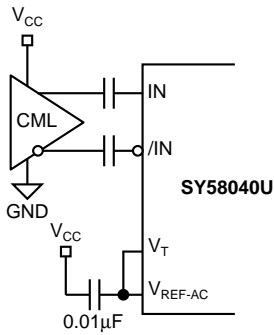


Figure 3d. CML Interface (AC-Coupled)

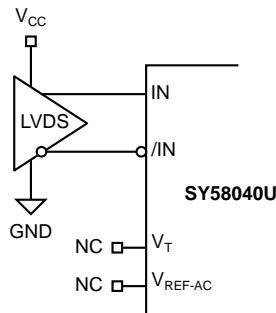
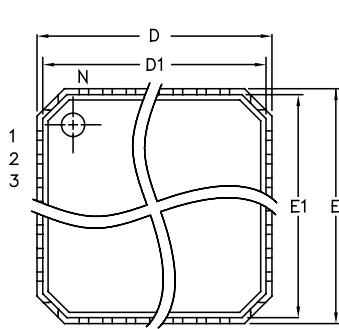


Figure 3e. LVDS Interface

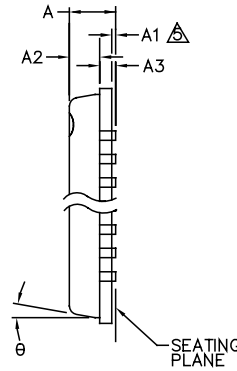
RELATED MICREL PRODUCTS AND SUPPORT DOCUMENTATION

Part Number	Function	Data Sheet Link
SY58040U	Ultra Precision 4x4 CML Crosspoint Switch with Internal Input/Output Termination	http://www.micrel.com/product-info/products/sy58040u.shtml
	MLF™ Application Note	www.amkor.com/products/notes_paper/MLF_AppNote.pdf
HBW Solutions	New Products and Applications	www.micrel.com/product-info/products/solutions.shtml

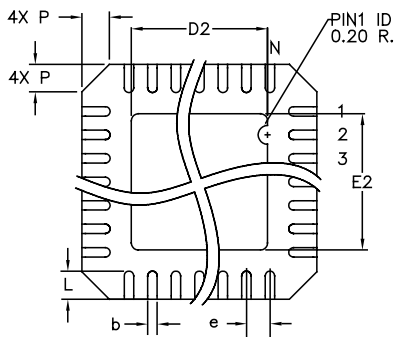
44 LEAD MicroLeadFrame™ (MLF-44)



TOP VIEW

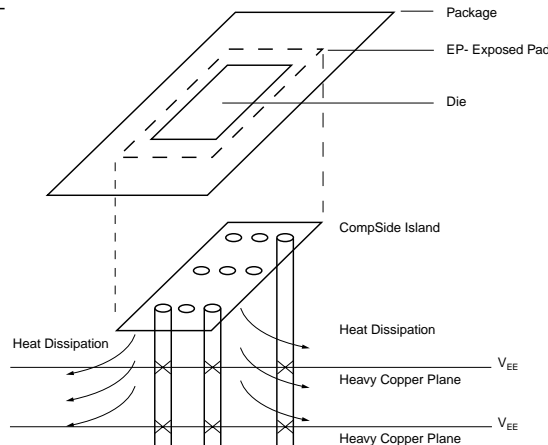


	DIMENSION (mm)		
	MIN.	NOM.	MAX.
A	—	0.85	0.90
A1	0.00	0.01	0.05
A2	—	0.65	0.70
A3	0.20 REF.		
D	7.00 BSC		
D1	6.75 BSC		
D2	3.15	3.30	3.45
E	7.00 BSC		
E1	6.75 BSC		
E2	3.15	3.30	3.45
θ	12°		
P	0.24	0.42	0.60
e	0.50 BSC		
N	44		
L	0.50	0.60	0.75
b	0.18	0.23	0.30



BOTTOM VIEW

- NOTE:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
 2. N IS THE NUMBER OF TERMINALS. THE NUMBER OF TERMINALS PER SIDE IS N/4.
 3. THE PIN#1 IDENTIFIER MUST BE EXISTED ON THE TOP SURFACE OF PACKAGE BY USING IDENTIFICATION MARK OR OTHER FEATURE OF PACKAGE BODY.
 4. PACKAGE WARPAGE MAX 0.05mm.
- ⚠ APPLIED FOR EXPOSED PAD AND TERMINALS.



PCB Thermal Consideration for 44-Pin MLF™ Package
(Always solder, or equivalent, the exposed pad to the PCB)

Package Notes:

1. Package meets Level 2 qualification.
2. All parts are dry-packaged before shipment.
3. Exposed pads must be soldered to a ground for proper thermal management.

MICREL, INC. 1849 FORTUNE DRIVE SAN JOSE, CA 95131 USA

TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB <http://www.micrel.com>

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